ST89 (E) Package Outline Drawing

NOTES:
1. PACKAGE BODY MATERIAL: MOLDING COMPOUND MP-180S OR EQUIVALENT.
2. LEAD MATERIAL: Cu w/ Ag SPOT PLATING.
3. LEAD PLATING: 100% MATTE TIN.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS]
5. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
6. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
7. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

<table>
<thead>
<tr>
<th>Part Number Suffix</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking [5][6]</th>
</tr>
</thead>
<tbody>
<tr>
<td>ST89</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1 [1]</td>
<td>HNNN XXXX</td>
</tr>
<tr>
<td>ST89E</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1 [2]</td>
<td>HNNN XXXX</td>
</tr>
</tbody>
</table>

[1] Max peak reflow temperature of 235 °C
[3] 4-Digit lot number XXXX
[4] 3-Digit part number NNN
ST89 (E) – 4 LEAD PLASTIC SOT89 PACKAGE

Suggested ST89 (E) PCB Land Pattern

NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
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Order On-line at www.hittite.com